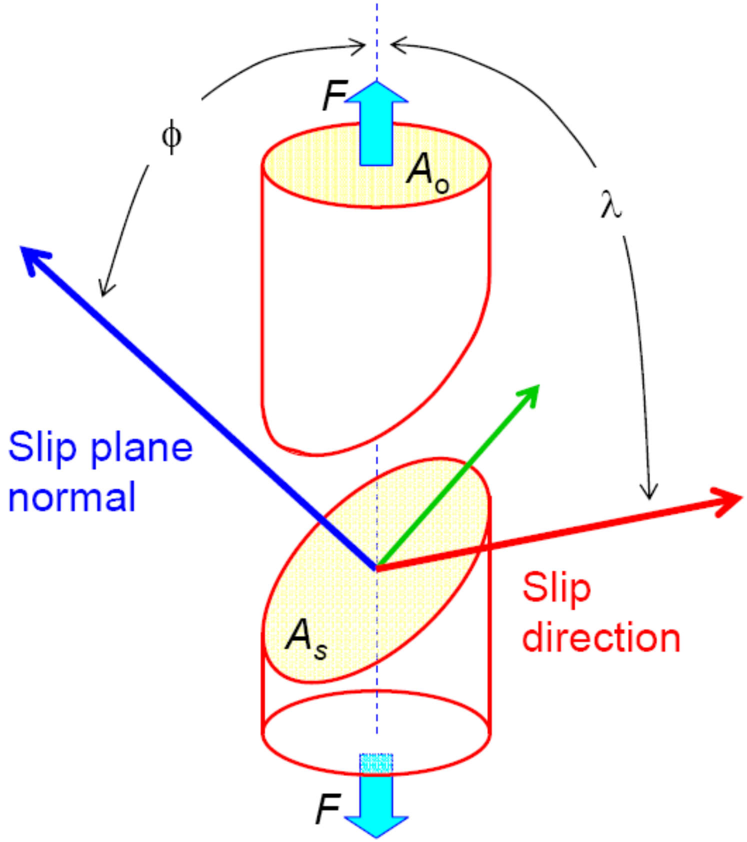
재료의 기계적 거동
(Mechanical Behavior of Materials)

Lecture 12 – Plastic Deformation

Heung Nam Han
Professor
Department of Materials Science & Engineering
College of Engineering
Seoul National University
Seoul 151-744, Korea
Tel : +82-2-880-9240
Fax : +82-2-885-9647
email : hnhan@snu.ac.kr
Office hours : Tuesday, Thursday 16:45~17:30
Homepage : http://mmmpdl.snu.ac.kr

Critical Resolved Shear Stress

- Plastic deformation is initiated at a critical stress the critical resolved shear stress (CRSS).
- The CRSS is the stress at which dislocations begin to move.



Resolved Shear Stress

$$\tau_{RSS} = \frac{F}{A_o} \underbrace{\cos\phi \cos\lambda}_{\text{Schmid Factor}} = \sigma / m$$

Talyor factor

Plastic flow is initiated when τ_{RSS} reaches a critical value, characteristic of the material, called *critical RSS*, when *m* $\tau_{CRSS} = \sigma_{ys}$ *(Schmid law)*.

Critical Resolved Shear Stress

Example problem I

Calculate the tensile yield stress that is applied along the $[1\bar{2}0]$ axis of a gold crystal to cause slip on the $(1\bar{1}\bar{1})[0\bar{1}1]$ slip system. The critical resolved shear stress is 10 MPa.

Example II: FCC Cu with Loading axis [112]

- What is most likely initial slip system?
- If CRSS is 50 MPa, what is the tensile yield stress at which Cu will start to deform plastically?

Slip Plane n	Slip direction s	n*l cosϕ	s*l cosλ	Schmid factor cosϕcosλ	σ (MPa)
(111)	$[\bar{1}10]$ $[\bar{1}01]$ $[0\bar{1}1]$	$2\sqrt{2}/3$	0 $\sqrt{3}/6$ $\sqrt{3}/6$	0 $\sqrt{6}/9$ $\sqrt{6}/9$	Not def. 184 184
$(\bar{1}11)$	$[110]$ $[101]$ $[0\bar{1}1]$	$\sqrt{2}/3$	$\sqrt{3}/3$ $-\sqrt{3}/2$ $\sqrt{3}/6$	$\sqrt{6}/9$ $-\sqrt{6}/6$ $\sqrt{6}/18$	184 - 122 367
$(1\bar{1}1)$	$[110]$ $[\bar{1}01]$ $[011]$	$\sqrt{2}/3$	$\sqrt{3}/3$ $-\sqrt{3}/6$ $\sqrt{3}/2$	$\sqrt{6}/9$ $-\sqrt{6}/18$ $\sqrt{6}/6$	184 - 367 122
$(11\bar{1})$ $=(\bar{1}\bar{1}1)$	$[\bar{1}10]$ $[101]$ $[011]$	0	0 $\sqrt{3}/2$ $\sqrt{3}/2$	0 0 0	Not def. Not def. Not def.

Smallest stress to cause slip (yielding)

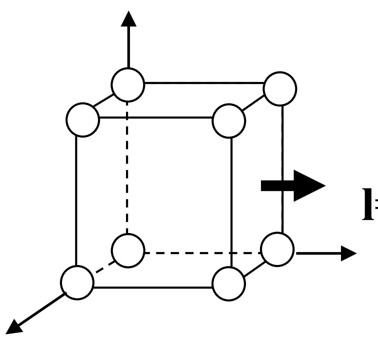
Initial Slip Systems (plane, direction) are then $(\bar{1}11)[101]$, $(1\bar{1}1)[011]$

Example III:

Crystal with simple cubic structure :
slip planes {100} and slip directions <010>

Load is applied along [010].
Determine Schmid factor and what slip occurs.

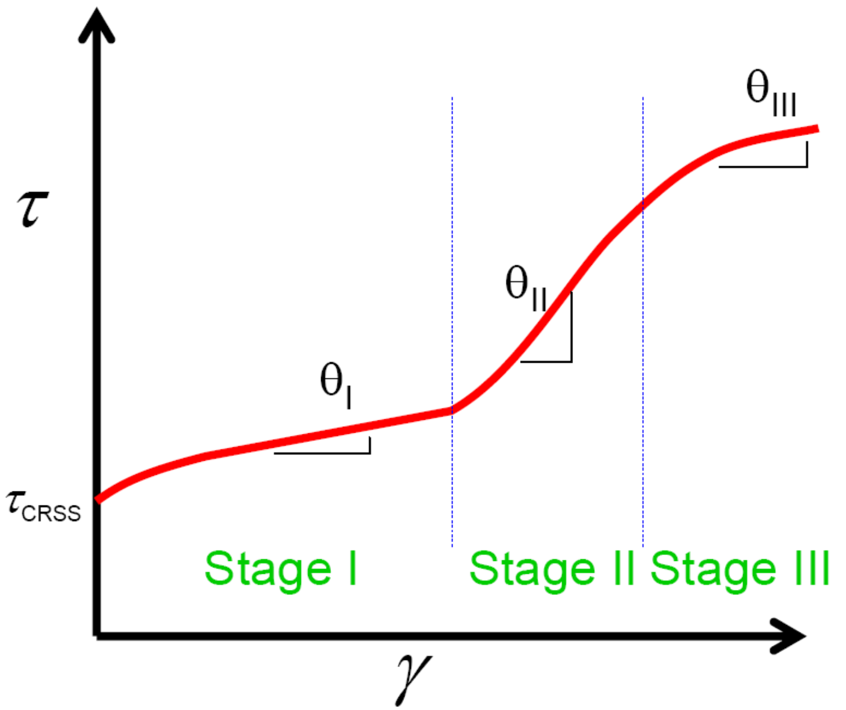
slip plane **n**	ϕ, cosϕ **n*l**	slip dir. **s**	λ, cosλ **s*l**	1/m cosϕcosλ
(100)	90°, 0	[010] [001]	0°, 1 90°, 0	0
(010)	0°, 1	[100] [001]	90°, 0 90°, 0	0
(001)	90°, 0	[100] [010]	90°, 0 0°, 1	0



l=[010]

Is there any slip? Why?
If no slip, what must happen finally to material as load is increased?

Deformation of single crystals



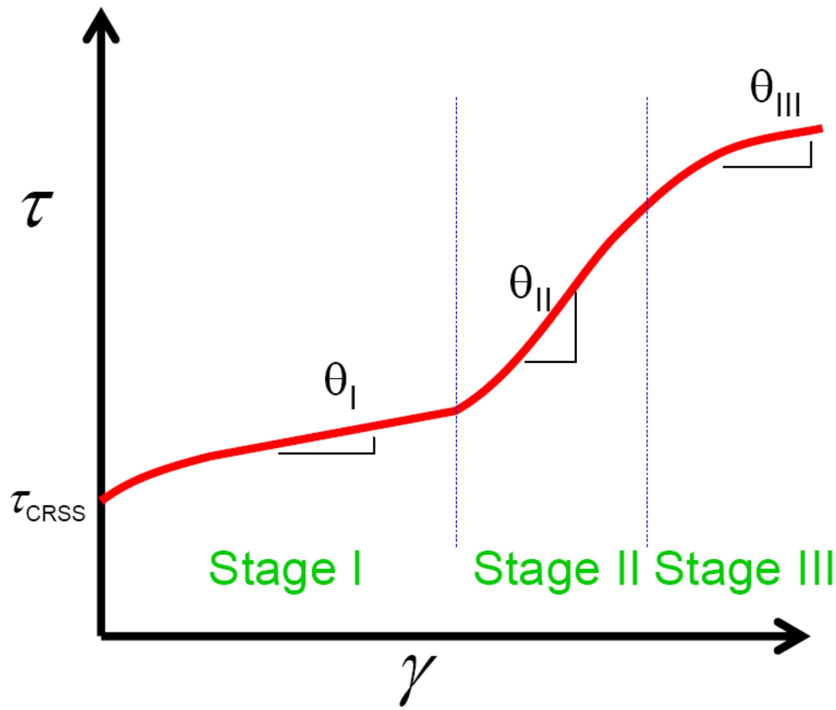
Stage I:

•After yielding, the shear stress for plastic deformation is essentially constant. There is little or no work hardening.

•This is typical when there is a single slip system operative. Dislocations do not interact much with each other. "Easy glide"

•Active slip system is one with maximum Schmid factor.

Deformation of single crystals



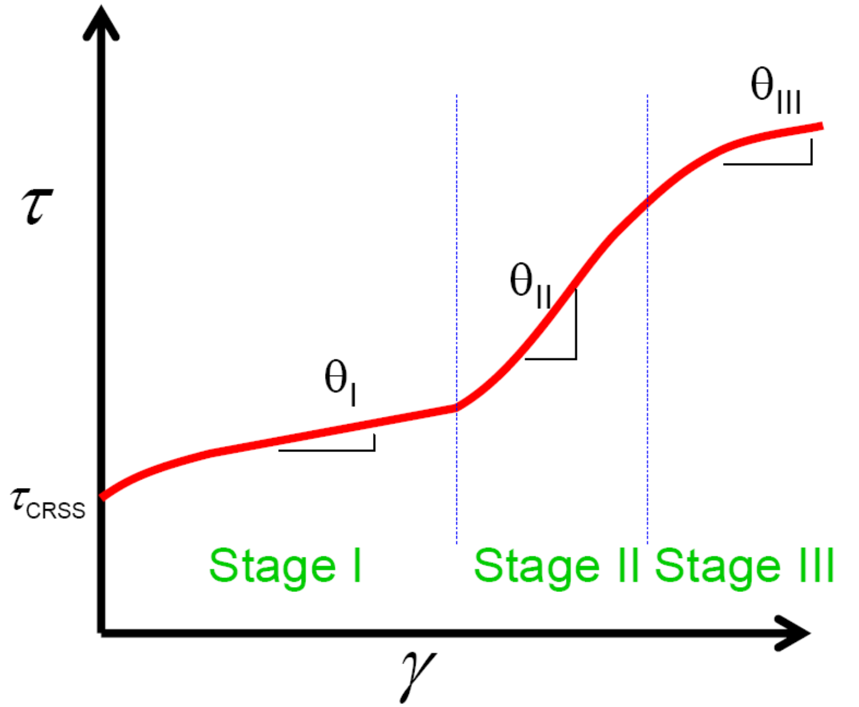
Stage II:

•The shear stress needed to continue plastic deformation begins to increase in an almost linear fashion. There is extensive work hardening (θ≅G/300).

•This stage begins when slip is initiated on multiple slip systems.

•Work hardening is due to interactions between dislocations moving on intersecting slip planes.

Deformation of single crystals

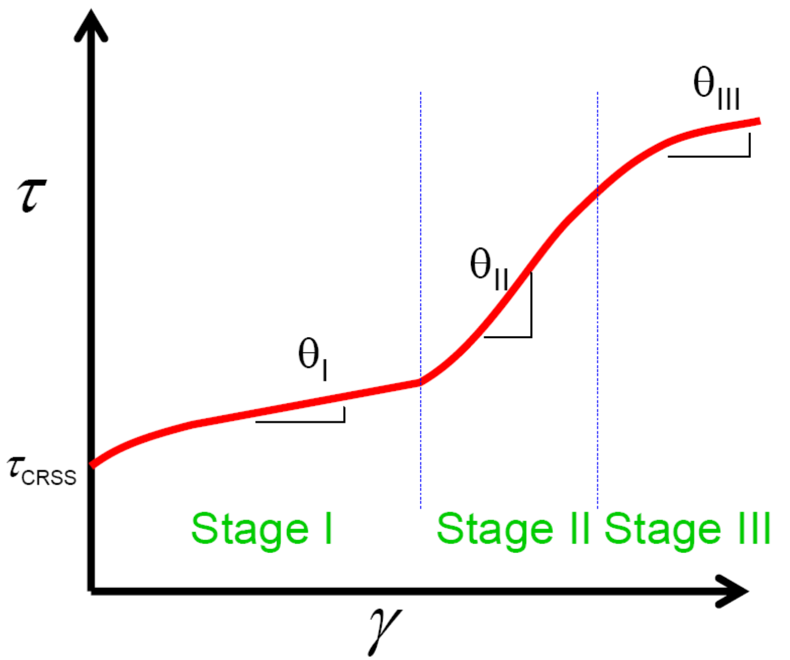


Stage III:

•There is a decreasing rate of work hardening.

•This decrease is due to an increase in the degree of cross slip resulting in a parabolic shape to the curve.

Deformation of single crystals



Effect of Temperature:

•Increasing T results in a decrease in the extent of Stage I and Stage II.

•Stage I:–Initiation of secondary slip systems is easier.

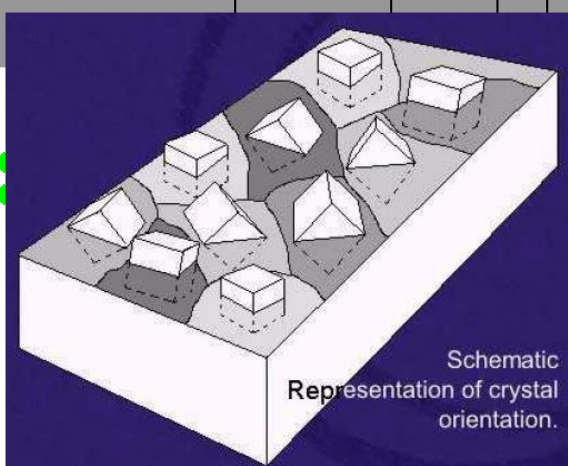
•Stage II:–Cross slip is easier.

Stacking Fault Energy (SFE) in FCC metals:

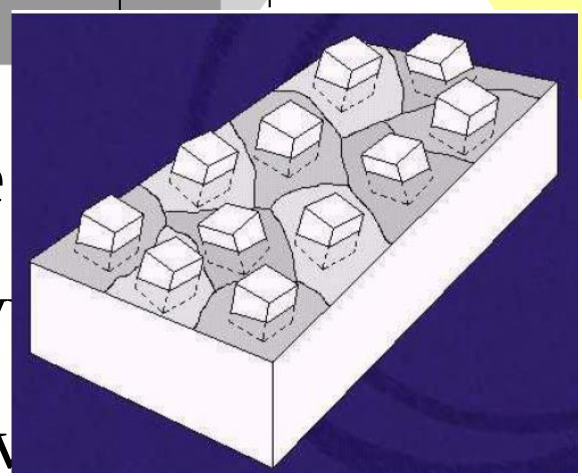
•Decrease SFE, decrease cross slip

•This increases the stress level needed to have a transition from Stage II to Stage III.

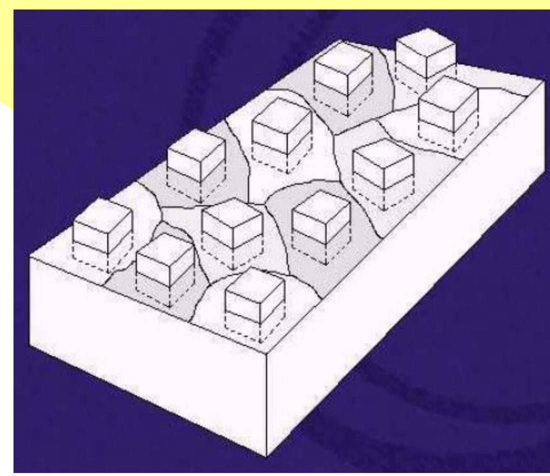
Crystal orientation: Miller Indices



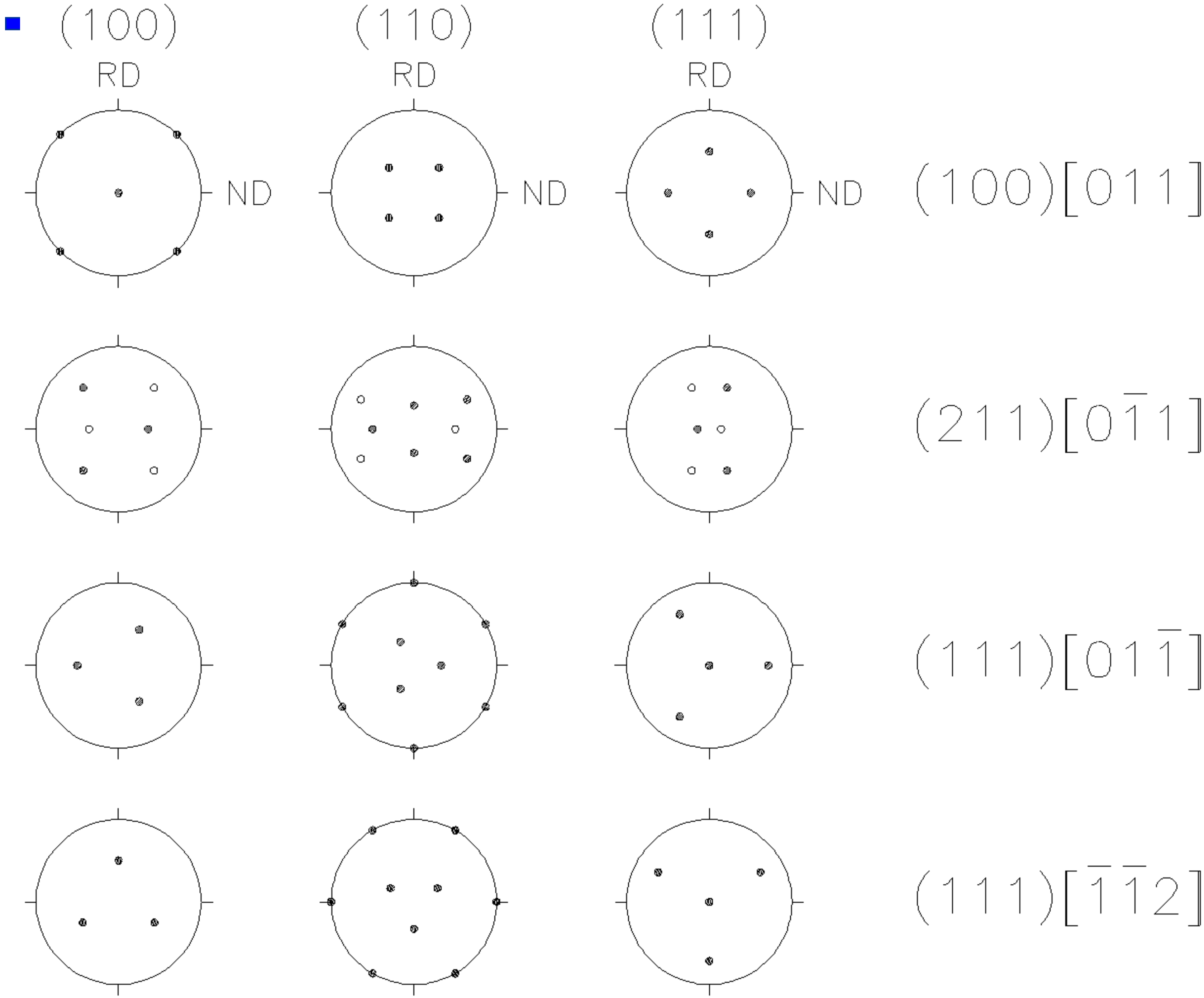
Random orientation



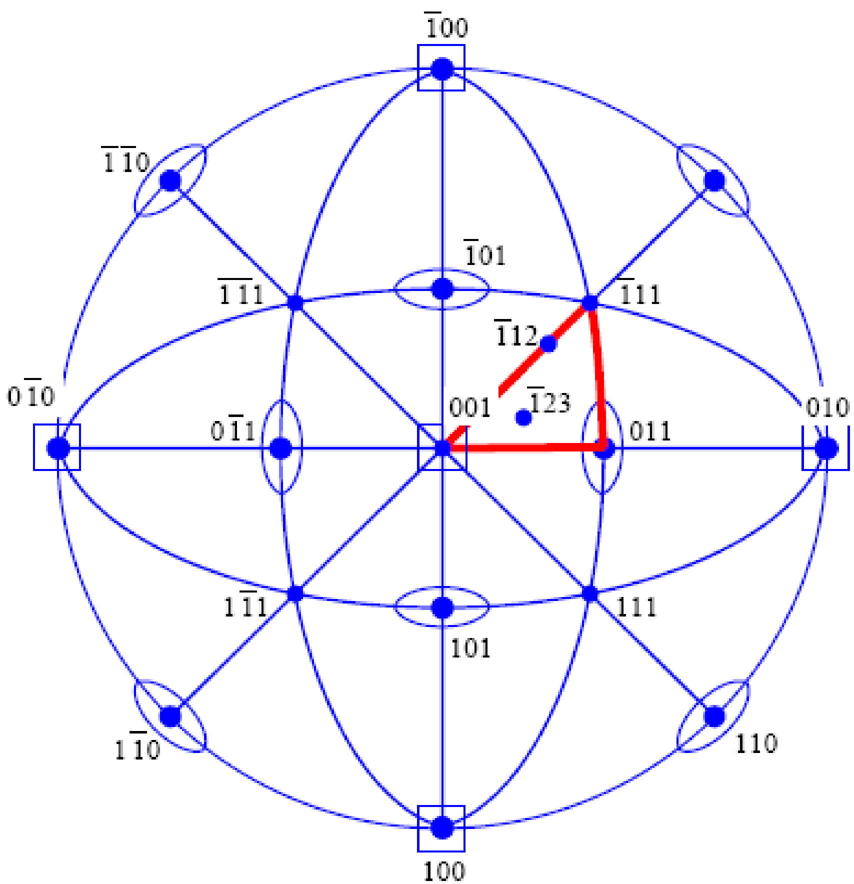
Preferred orientation



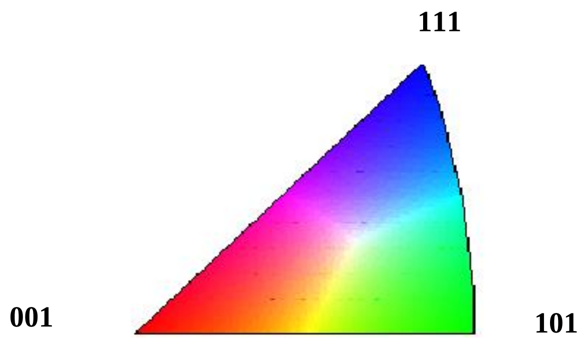
Highly oriented - close to a single crystal

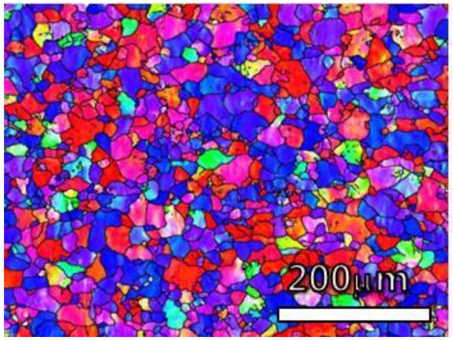

(100)
(110)
(111)
RD
RD
RD
ND
ND
ND
$(100)[011]$
$(211)[0\bar{1}1]$
$(111)[01\bar{1}]$
$(111)[\bar{1}\bar{1}2]$

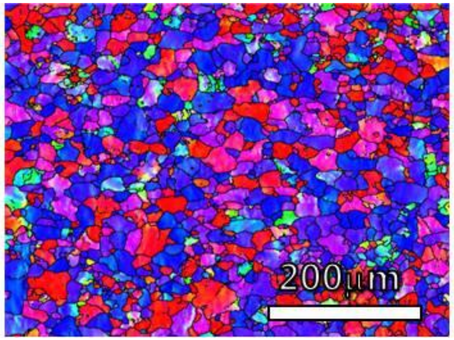
[001] stereographic projection of cubic crystal

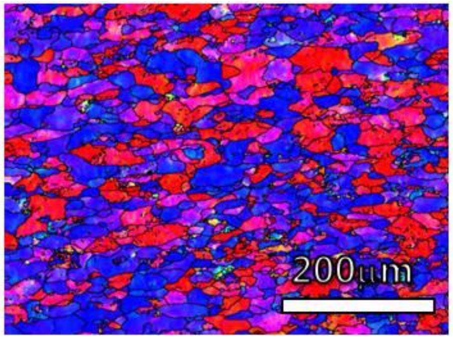


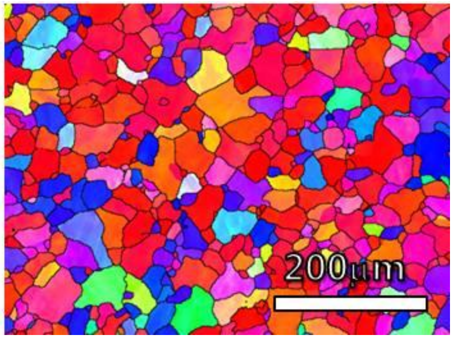
Orientation (ND) maps



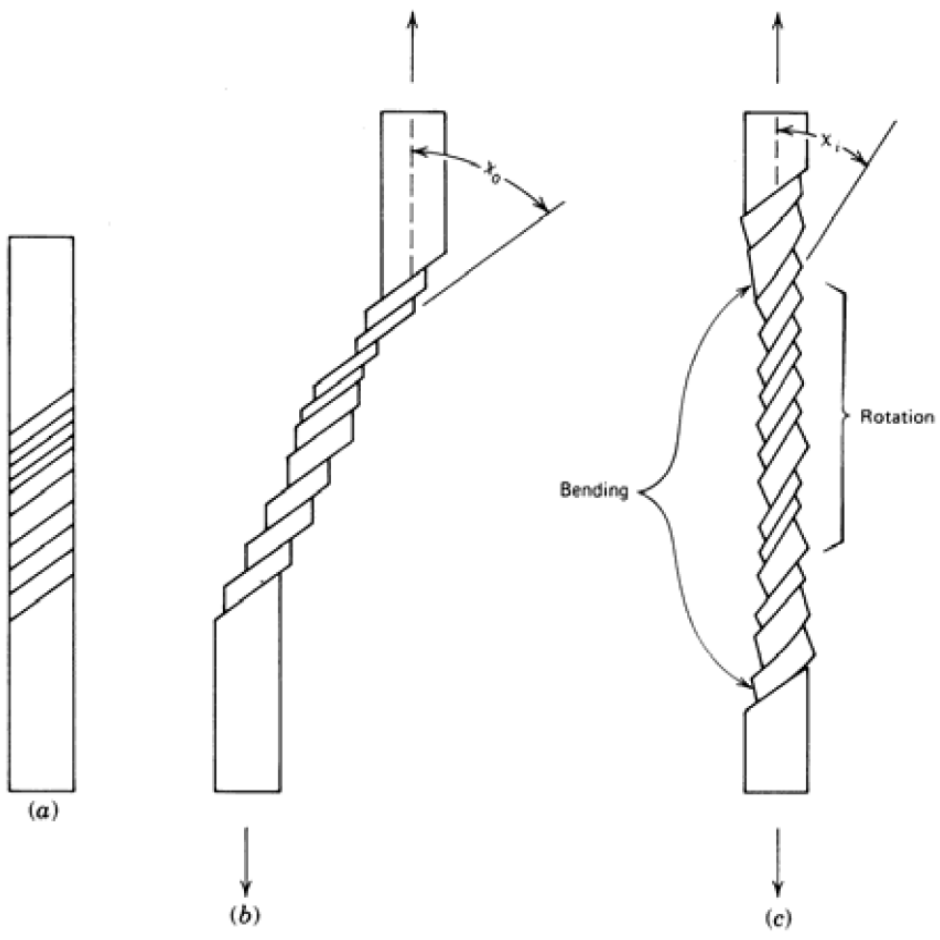








What happens to a single crystal when it starts to yield?

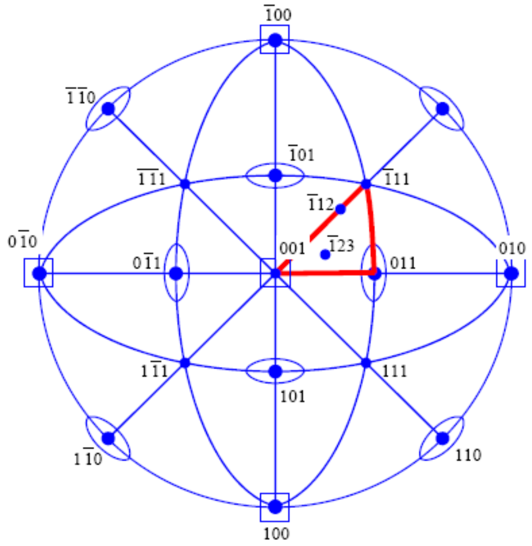


•Consider a single crystal oriented for slip on planes oriented χ degrees from the tensile axis.

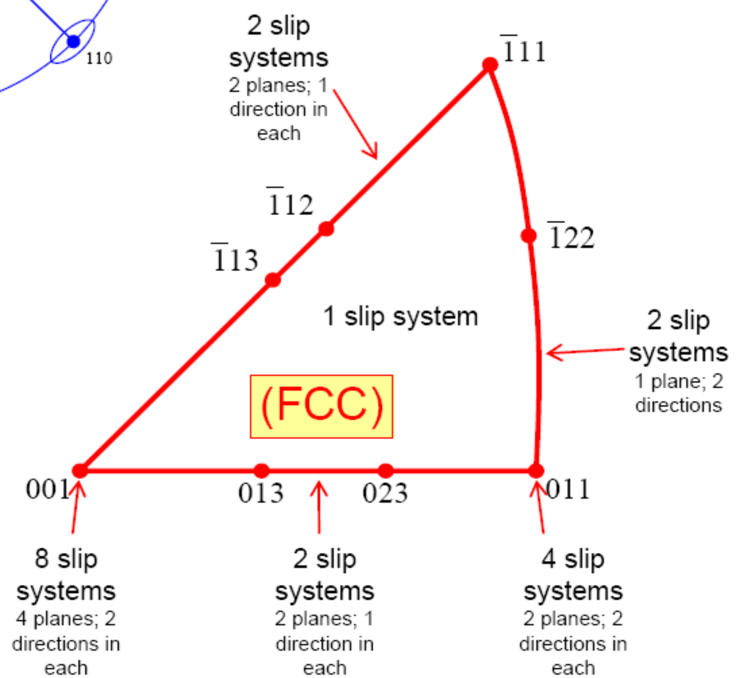
•Ideally, crystal planes will "glide" over one another without changing their relative orientation to the load axis.

•However, during tensile testing, the ends of the tensile bar are constrained. Thus, the crystal planes cannot glide freely. They are forced to rotate towards the tensile axis ($\chi_i < \chi_o$) .

[001] stereographic projection of cubic crystal



Standard Triangle



What happens to a single crystal when it starts to yield?

- When (as is usual) testing constrains the upper and lower ends keeping them aligned, the crystal will rotate such that the angle between the stress axis and the slip direction decreases.
- Thus, the Schmid factor changes! This can lead to the initiation of slip on a different system.

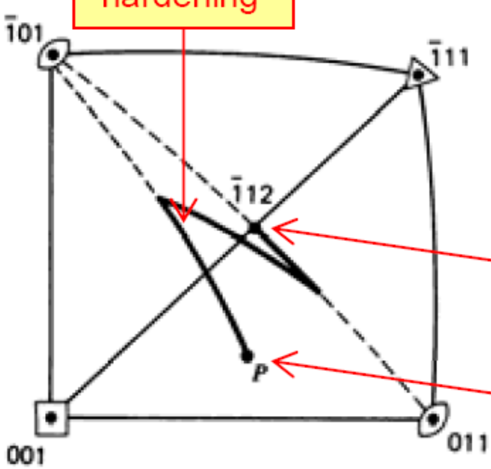


FIGURE 3.9 **Lattice rotation of FCC crystal involving "overshoot" of primary and conjugate slip systems.**

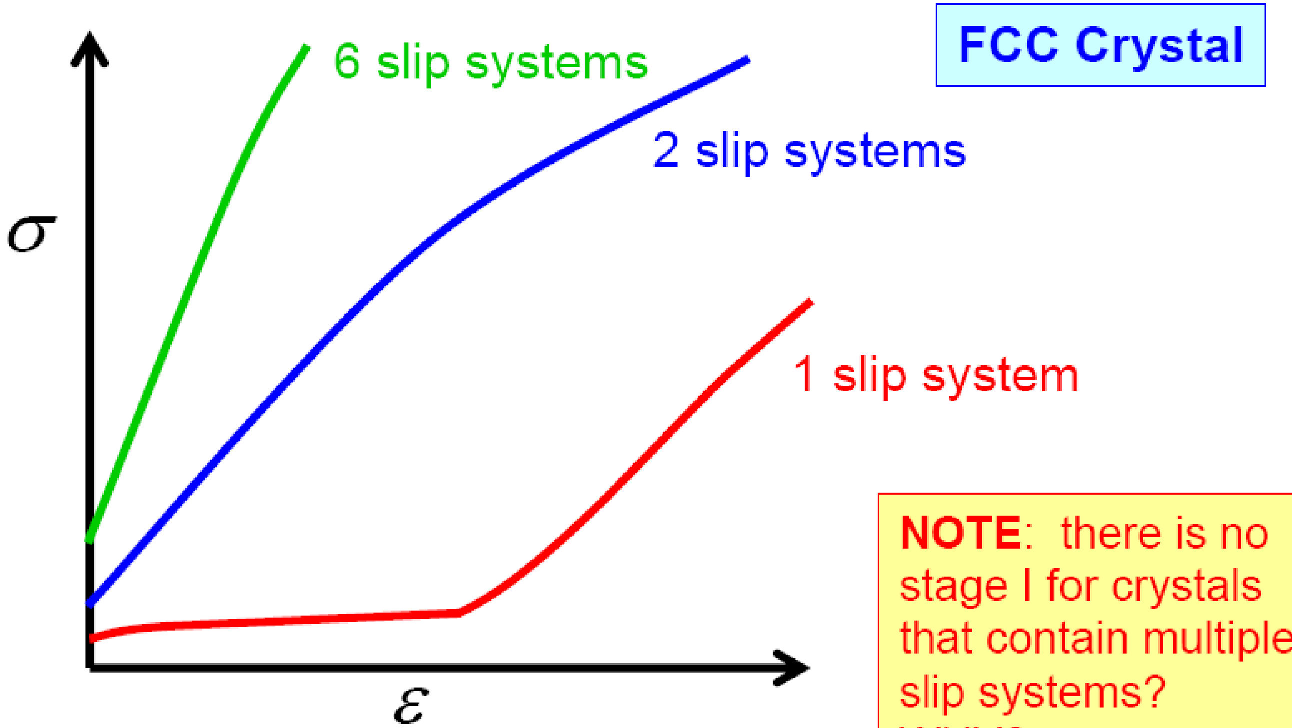
$$[\bar{1}12] = \sum [\bar{1}01] + [011]$$

- The crystal will continue to rotate with deformation occurring on alternating slip systems.
- This will continue until the load axis reaches [-112] where the crystal will neck down until failure without changing orientation.

Influence of stress axis orientation

The stress axis orientation plays a **major role** in the stress-strain behavior of a single crystal

More slip systems means a "harder" material.

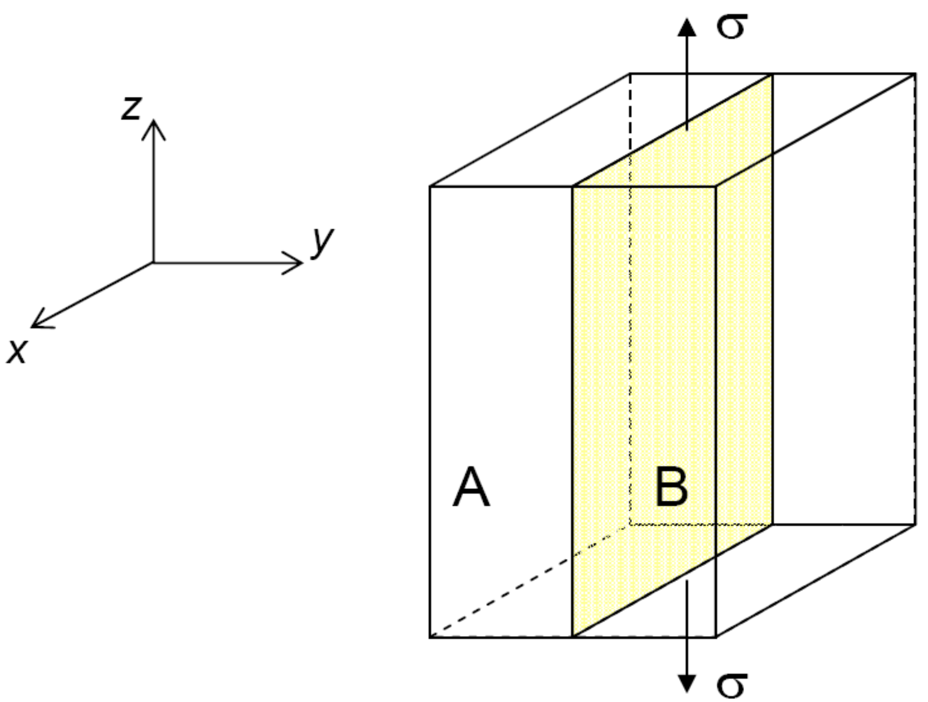


NOTE: there is no stage I for crystals that contain multiple slip systems? WHY?

Implications for polycrystalline materials

•Plastic deformation within an individual grain is constrained by the neighboring grains.

•Since plastic deformation of a single grain is restrained by its neighboring grain, a polycrystalline material will have an intrinsically greater resistance to plastic flow than would a single crystal.



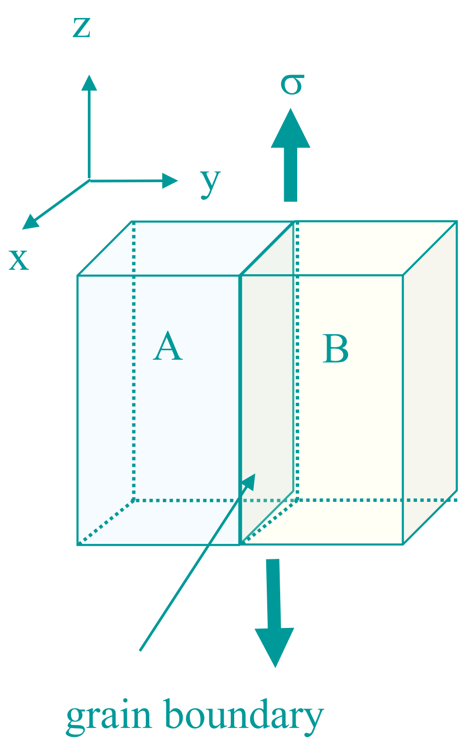
$$\varepsilon_x^A = \varepsilon_x^B$$

$$\varepsilon_z^A = \varepsilon_z^B$$

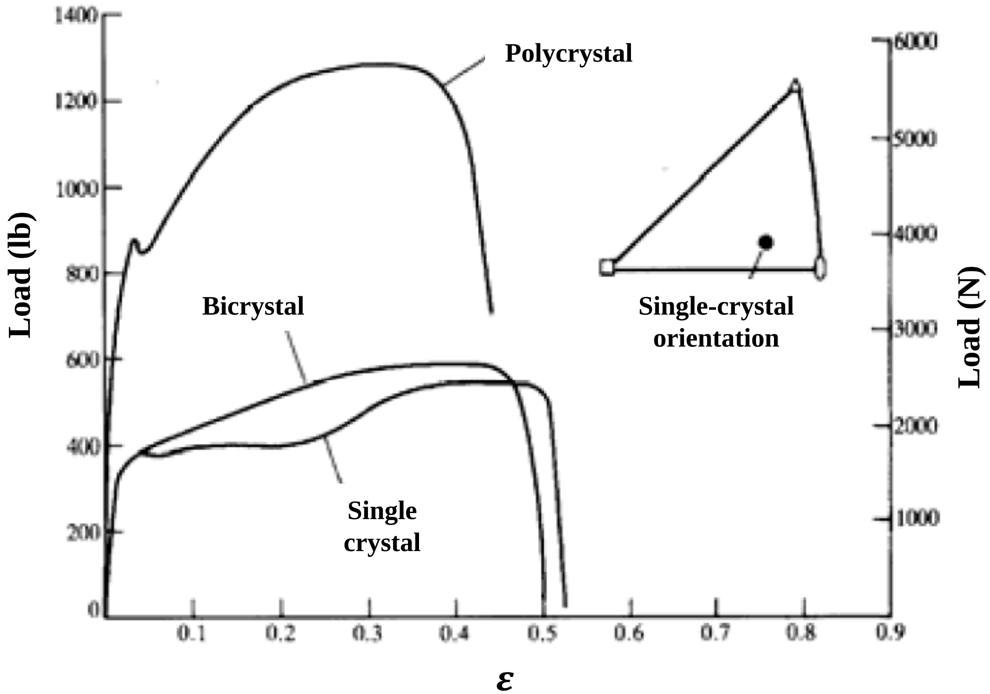
$$\gamma_{xz}^A = \gamma_{xz}^B$$

Required to maintain continuity of the grain boundary

Implications for polycrystalline materials

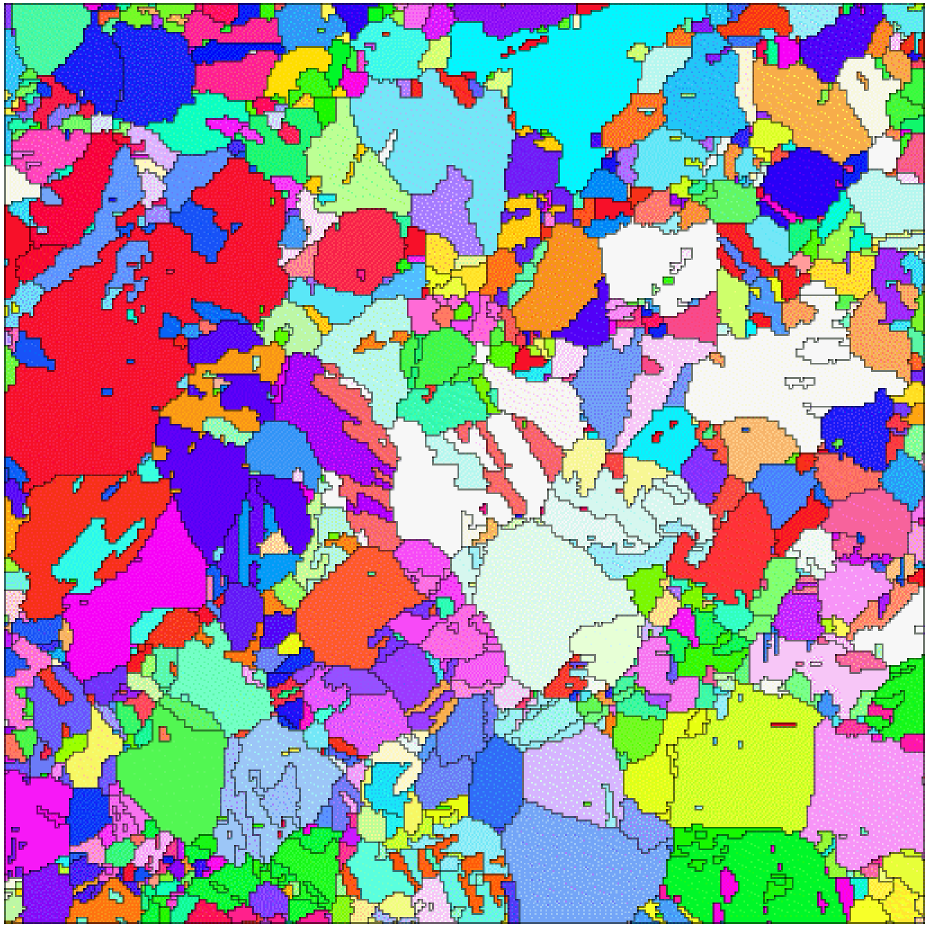


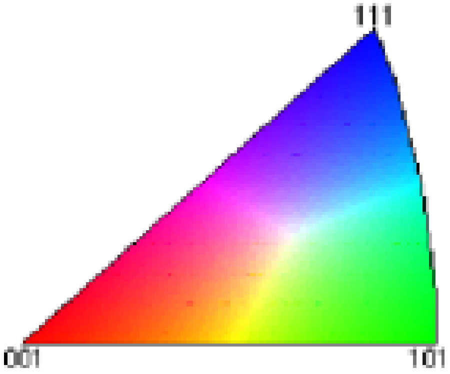
Because *one grain* has a **larger value of cos ϕ cos λ** [smaller Taylor factor (1/m)], the above constraints restrict the deformation of this more favorably oriented grain and result in a *higher Yield Strength* (greater work-hardening response of the bicrystal.



Niobium (bcc)

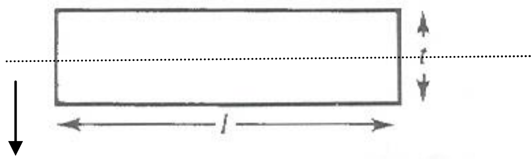
Implications for polycrystalline materials



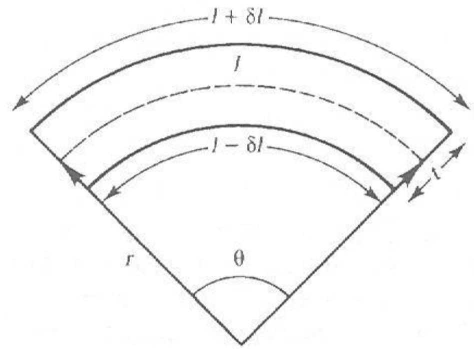


Geometrically necessary dislocation (GND), Statistically stored dislocation (SSD)

Plastic bending of a crystal



Slip plane and direction

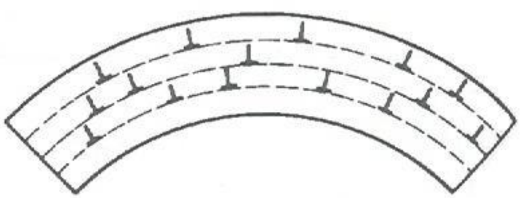


Strain gradient=strain difference/thickness

$$\left(\frac{\delta l}{l} - \frac{-\delta l}{l}\right)/t = \frac{2\delta l}{lt}$$

$$\textit{difference of the atomic planes}$$

$$= \frac{(l+\delta l)}{b} - \frac{(l-\delta l)}{b}$$



$$\textit{density of geometrical dislocation}$$

$$\rho_s = \frac{\textit{the number of dislocation}}{\textit{surface area}} = 2\frac{\delta l}{blt} = \frac{\textit{strain gradient}}{b}$$

Generally,

$$\rho_s = \alpha \frac{\textit{strain gradient}}{b}$$

Geometrically necessary dislocation (GND)